

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
19 May 2005 (19.05.2005)

PCT

(10) International Publication Number
WO 2005/044920 A1

(51) International Patent Classification⁷: C08L 83/06,
C09J 183/06, C09D 183/06

Ichihara-shi, Chiba 2990108 (JP). **TOGASHI, Atsushi**
[JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd., 2-2,
Chigusa-kaigan, Ichihara-shi, Chiba 2990108 (JP).

(21) International Application Number:
PCT/JP2004/016716

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG,
KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG,
MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH,
PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN,
TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(22) International Filing Date:
4 November 2004 (04.11.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
2003-378521 7 November 2003 (07.11.2003) JP

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,
FR, GB, GR, HU, IE, IS, IT, LU, MC, NL, PL, PT, RO, SE,
SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,
GW, ML, MR, NE, SN, TD, TG).

(71) Applicant (for all designated States except US): **DOW
CORNING TORAY SILICONE CO., LTD.** [JP/JP]; 1-3,
Marunouchi 1-chome, Chiyoda-ku, Tokyo 1000005 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **MORITA, Yoshit-
sugu** [JP/JP]; c/o Dow Corning Toray Silicone Co., Ltd.,
2-2, Chigusa-kaigan, Ichihara-shi, Chiba 2990108 (JP).
ISSHIKI, Minoru [JP/JP]; c/o Dow Corning Toray
Silicone Co., Ltd., 2-2, Chigusa-kaigan, Ichihara-shi,
Chiba 2990108 (JP). **UEKI, Hiroshi** [JP/JP]; c/o Dow
Corning Toray Silicone Co., Ltd., 2-2, Chigusa-kaigan,

Published:

— with international search report

For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.

WO 2005/044920 A1

(54) Title: CURABLE SILICONE COMPOSITION AND CURED PRODUCT THEREOF

(57) Abstract: A curable silicone composition includes: (A) an organopolysiloxane represented by the siloxane unit formula (1) given below and having at least two univalent organic groups that contain epoxy groups and are free of aromatic rings: $[R^1_3SiO_{1/2}]_a [R^2_2SiO_{2/2}]_b [R^3SiO_{3/2}]_c$ (where R^1 , R^2 , and R^3 are univalent organic groups, at least two of which are univalent organic groups which contain epoxy groups and are free of aromatic rings; more than 20 mole % of R^3 are aryl groups; $a + b + c = 1$; on average, "a" satisfies the following condition: $0 \leq a \leq 0.8$; on average, "b" satisfies the following condition: $0 \leq b \leq 0.8$; and, on average, "c" satisfies the following condition: $0.2 \leq c \leq 1.0$); (B) a linear-chain organopolysiloxane having at least two univalent organic groups that contain phenolic hydroxyl groups; and (C) a curing accelerator.